DATA SHEET

Rapid

Drafting Aids

Order code	Manufacturer code	Description
34-4450	n/a	PACK 5 PRESS-N-PEEL TRANSFERS (RE)

Press-n-Peel PCB Transfers

Instructions

1. Clean the copper board by scrubbing the surface with a wet Scotchbrite or Steelwool, thus removing any surface oxidation and surface oil. Some users prefer to etch the cleaned board for 30 seconds to further de-oxidise the copper and provide better adhesion for the transfer process.

2. **Press-n-Peel** will only work with plain paper copies and laser printers to produce circuit boards. Just about any CAD program can be used to create an image. PC layouts from magazines and dot matrix printed drawings can be used with a photocopier. The copier or printer should be adjusted to give the darkest image without leaving tell-tale smudges on the non-image/non-trace area.

3. The circuit image should be printed such that trace areas are black lines, and non-trace areas are white. Be sure that the trace image that is produced appears as if you are looking through the PC board from the component side and seeing the pattern, thus writing will appear as a mirror image. The image is placed on the emulsion side (dull side) of the **Press-n-Peel** material.

4. Place **Press-n-Peel** into the copier or laser printer and proceed to print/copy the image, just as with plain paper. A single sheet at a time works best with most machines. Some machines require a piece of paper as a backing sheet to properly feed.

5. Cut the image out of the sheet leaving a minimum of ¼" around the circuit pattern. Have a clean piece of circuit board ready for application. A household clothes iron is used to apply **Press-n-Peel**. The temperature setting is dependent upon the type of toner used in your copier or laser printer. The best place to start is with a setting in the lower region of "Steam". Usually about 200-250 degrees F. (Not Centigrade.)

6. Place **Press-n-Peel** with the image face down (image contacting the circuit board material). Place the board with film on top of a piece of wood or similar insulating material. Carefully apply the hot iron to the backside of the film (shiny side up), concentrating on one corner first until adhered. Continue to apply the heat with the iron using a circular motion, especially towards the outer edges, until you sense the film has stick approx. 60 - 90 second. The larger the area tile longer the time.

7. The image will become dark and pronounced through the film back. Evenly heat the entire surface of the board to a consistent temperature.

8. Allow the board to go cold before attempting to remove the backing film. Lift a corner slowly, at this stage if the film has not stuck down properly it can be re-ironed on, before removing the backer. After the backer has been removed any defective areas can be touched up using an etch resist pen.

9. The board is now ready for etching, drilling, plating etc in the normal fashion.